

Amendments to the Claims:

Claims 1-17 (Cancelled).

18. (Currently Amended) A multi-layer board comprising:
a ceramic layer having a first side and a second side opposite said first side, said ceramic layer having a dielectric constant;
an impedance element on said ceramic layer;
a first resin layer over said first side of said ceramic layer, said first resin layer having a dielectric constant lower than said dielectric constant of said ceramic layer;
a second resin layer over said second side of said ceramic layer;
a third resin layer over said first resin layer; and
~~a polyimide film between said first resin layer and said third resin layer; and~~
~~a capacitor on said polyimide film~~
a strip line on said first resin layer.

19. (Previously Presented) The multi-layer board of claim 18, further comprising an electronic component mounted on said first resin layer.

Claim 20 (Cancelled).

21. (Previously Presented) The multi-layer board of claim 18, further comprising a strip line on said third resin layer.

22. (Previously Presented) The multi-layer board of claim 18, further comprising an electronic component mounted on said third resin layer.

23. (Previously Presented) The multi-layer board of claim 18, further comprising a fourth resin layer between said first resin layer and said third resin layer.

24. (Previously Presented) The multi-layer board of claim 18, wherein said impedance element comprises a patterned inductor.

25. (Previously Presented) The multi-layer board of claim 24, wherein said patterned inductor comprises a laser-trimmed patterned inductor.

26. (Previously Presented) The multi-layer board of claim 24, wherein said first resin layer has a first side facing said ceramic layer and has a second side opposite said first side of said first resin layer, further comprising a ground pattern on said second side of said first resin layer, said ground pattern and said patterned inductor being arranged such that no portion of said ground pattern is located on said second side of said first resin layer opposite a portion of said first side of said first resin layer facing said patterned inductor.

Claim 27 (Cancelled).

28. (Previously Presented) The multi-layer board of claim 18, wherein said impedance element comprises a resistor.

29. (Previously Presented) The multi-layer board of claim 28, wherein said resistor comprises a laser-trimmed resistor.

30. (Previously Presented) The multi-layer board of claim 18, wherein said impedance element comprises a first impedance element on said first side of said ceramic layer, further comprising a second impedance element on said second side of said ceramic layer.

31. (Previously Presented) The multi-layer board of claim 18, further comprising a strip line on said first resin layer.

32. (Currently Amended) A multi-layer board comprising:
a ceramic layer having a first side and a second side opposite said first side;
an impedance element including a patterned inductor on said ceramic layer;
a resin layer over said first side of said ceramic layer, said resin layer having a first side facing said first side of said ceramic layer and having a second side opposite said first side of said resin layer; and
a ground pattern on said second side of said resin layer, said ground pattern and said patterned inductor being arranged such that no portion of said ground pattern is located on a portion of said second side of said resin layer opposite a portion of said first side of said resin layer facing said patterned inductor so as to increase a Q-factor of said patterned inductor.

33. (Previously Presented) The multi-layer board of claim 32, further comprising an electronic component mounted on said resin layer.

34. (Previously Presented) The multi-layer board of claim 32, wherein said resin layer comprises a first resin layer over said first side of said ceramic layer, further comprising a second resin layer over said second side of said ceramic layer.

35. (Previously Presented) The multi-layer board of claim 34, further comprising a strip line on said second resin layer.

36. (Previously Presented) The multi-layer board of claim 34, further comprising a third resin layer over said first resin layer.

37. (Previously Presented) The multi-layer board of claim 36, further comprising a strip line on said third resin layer.

38. (Previously Presented) The multi-layer board of claim 36, further comprising an electronic component mounted on said third resin layer.

39. (Previously Presented) The multi-layer board of claim 36, further comprising a fourth resin layer between said first resin layer and said third resin layer.

40. (Previously Presented) The multi-layer board of claim 36, further comprising:
a polyimide film between said first resin layer and said third resin layer; and
a capacitor on said polyimide film.

41. (Previously Presented) The multi-layer board of claim 32, wherein said patterned inductor comprises a laser-trimmed patterned inductor.

42. (Previously Presented) The multi-layer board of claim 32, wherein said impedance element comprises a first impedance element on said first side of said ceramic layer, further comprising a second impedance element on said second side of said ceramic layer.

43. (Previously Presented) The multi-layer board of claim 32, further comprising a strip line on said resin layer.

44. (New) The multi-layer board of claim 18, further comprising:
a polyimide film between said first resin layer and said third resin layer; and
a capacitor on said polyimide film.

45. (New) The multi-layer board of claim 18, wherein said third resin layer has a dielectric constant lower than said dielectric constant of said ceramic layer.

46. (New) The multi-layer board of claim 18, wherein one of said first resin layer, said second resin layer, and said third resin layer is mounted on a board, said one of said first resin layer, said second resin layer, and said third resin layer having a thermal expansion coefficient substantially identical to a thermal expansion coefficient of said board.

47. (New) The multi-layer board of claim 32, wherein said resin layer has a dielectric constant lower than a dielectric constant of said ceramic layer.

48. (New) The multi-layer board of claim 32, wherein said resin layer is mounted on a board, said resin layer having a thermal expansion coefficient substantially identical to a thermal expansion coefficient of said board.